



DESOLDERING BRAID

SODER-WICK® BGA

The most effective, economical way to safely and completely remove solder from BGA pads and chips

- Sized and designed specifically for BGA pad and chip rework/repair
- Entire BGA pads cleaned in three to four passes
- Available in rosin and no-clean fluxes
- Packaged in ESD-safe static dissipative bobbins

SODER-WICK® ROSIN SD

The fastest, safest rosin flux desoldering braid packaged in static dissipative bobbins

- Packaged in ESD-safe (static dissipative) bobbins
- Minimizes the risk of damage associated with static electricity
- Noncorrosive Type R rosin flux
- Minimizes the risk of heat damage to the board
- Will not leave ionic contamination on boards

SODER-WICK® NO CLEAN SD

The fastest, cleanest no-clean flux desoldering braid packaged in static dissipative bobbins

- Packaged in ESD-safe (static dissipative) bobbins
- Minimizes the risk of damage associated with static electricity
- Patented noncorrosive, halide free, organic no-clean flux
- Desolders up to 40% faster than competitive no-clean braids and leaves boards cleaner
- Meets Bellcore TR-NWT-000078 and IPC SF-818 for Surface Insulation Resistance

For more information please contact:

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